



## Final Product Change Notification

201312024F01U02

**Issue Date:** 24-May-2014  
**Effective Date:** 22-Aug-2014

**UPDATE**

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# QUALITY

### Change Category

<input checked="" type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

## SOT223 Copper Wire - Automotive

### Details of this Change

NXP will introduce variants of SOT223 PowerMOS devices which will use copper wirebonds rather than gold. This will ensure a commercially sustainable platform for the continued manufacture of these devices. The product performance will be unchanged.

#### Why do we Implement this Change

Copper wire has less electrical resistance than Gold, is more resilient and performs better in high current analogue devices such as Power MOSFETS

#### Identification of Affected Products

Replacement part type created, see Parts Affected list

### Product Availability

#### Sample Information

Samples are available upon request

#### Production

Planned first shipment 29-Sep-2014

### Update Information

Presentation slides, PCN201312024F01\_Update1.pdf, have been attached to give further detail with respect to each change category.

Update to Product Availability, planned first shipment date changed to 29th September 2014.

### Impact

no impact to the product's functionality anticipated.  
No change to the product's functionality.  
There is no change to the form, fit or function of the product.

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

N/A - Replacement part type created

#### **Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 23-Jun-2014.

#### **Remarks**

This product change notification is for your company internal use and for your use as Distributor towards your direct customers. You are responsible for the correct circulation of this information to your direct customers.

NXP does not accept liability for any failure to notify your direct customers of this change within the appropriate timeframe, or for any other incorrect further distribution of this information.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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